

## **Claims**

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Cancelled)
2. (Cancelled)
3. (Cancelled)
4. (Currently Amended) The method according to claim ~~[[1]]~~14, wherein the rim of the shield can is provided with the extra amount of solder by a screen-printing process.
5. (Cancelled)
6. (Cancelled)
7. (Cancelled)
8. (Cancelled)
9. (Cancelled)
10. (Cancelled)
11. (Cancelled)
12. (Cancelled)
13. (Cancelled)

14. (New) A method for providing a PCB (printed circuit board) with a shield can comprising a metal shell having a free rim, said method comprising the steps of:  
providing a shield can comprising a metal shell having a free rim and recesses provided at the rim;  
providing the PCB with solder;  
placing the shield can on the PCB with the rim towards the PCB;  
heating the PCB and the shield can to a temperature above a melting temperature of the solder; and  
cooling the PCB and the shield can, wherein an extra amount of solder is applied to the recesses of the shield can before the shield can is placed on the PCB.

15. (New) A method for providing a PCB (printed circuit board) with a shield can comprising a metal shell having a free rim, said method comprising the steps of:  
providing a shield can comprising a metal shell having a free rim and indentations at the rim;  
providing the PCB with solder;  
placing the shield can on the PCB with the rim towards the PCB;  
heating the PCB and the shield can to a temperature above a melting temperature of the solder; and  
cooling the PCB and the shield can, wherein an extra amount of solder is applied to the indentations of the shield can before the shield can is placed on the PCB.